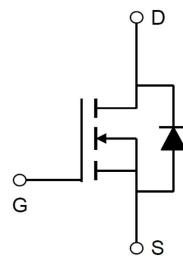
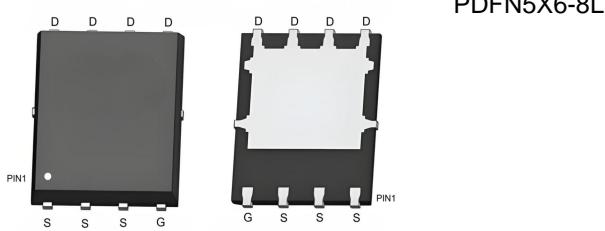


## N-Channel 30V(D-S) MOSFET

Product summary			Features
$V_{DS}$	30	V	<ul style="list-style-type: none"> <li>Advanced Trench Technology</li> <li>Low Gate Charge</li> </ul>
$R_{DS(ON)}$ (at $V_{GS}=10V$ ) Typ.	4.7	$m\Omega$	<b>Applications</b> <ul style="list-style-type: none"> <li>Load switching</li> <li>PWM Applications</li> <li>Power Management</li> </ul>
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ ) Typ.	7.7	$m\Omega$	
$I_D(T_c=25^\circ C)$	70	A	

### Pin Configuration



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAP70N03A	PDFN5X6-8L	13"	3000pcs

### Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_c=25^\circ C$	A
		$T_c=100^\circ C$	A
$I_{DM}$	Pulse Drain Current Tested <sup>A</sup>	280	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>B</sup>	56	mJ
$P_D$	Power Dissipation @ $T_c=25^\circ C$	67	W
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JC}$	Thermal Resistance-Junction to case max	1.9	°C/W

Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance <sup>C</sup>	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=30\text{A}$	--	4.7	6	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$	--	7.7	12	$\text{m}\Omega$
$V_{\text{SD}}$	Diode Forward Voltage	$I_{\text{S}}=1\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.2	V
Dynamic Parameters <sup>D</sup>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=15\text{V}$ $f=1\text{MHz}$	--	1614	--	pF
$C_{\text{oss}}$	Output Capacitance		--	245	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	215	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=30\text{A}$ $V_{\text{GS}}=10\text{V}$	--	33.7	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	8.5	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	7.5	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=15\text{V}$ $, R_{\text{GEN}}=3\Omega,$ $I_{\text{D}}=30\text{A},$ $V_{\text{GS}}=10\text{V}$	--	7.5	--	ns
$t_r$	Turn-on Rise Time		--	14.5	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	35.2	--	ns
$t_f$	Turn-off Fall Time		--	9.6	--	ns

A. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

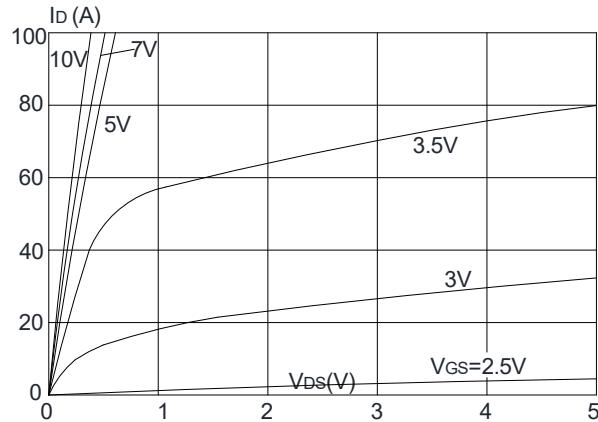
B. EAS condition:  $T_J=25^\circ\text{C}$ ,  $R_G=25\Omega$ ,  $V_{\text{DD}}=15\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $I_{\text{AS}}=15\text{A}$ .

C. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$ .

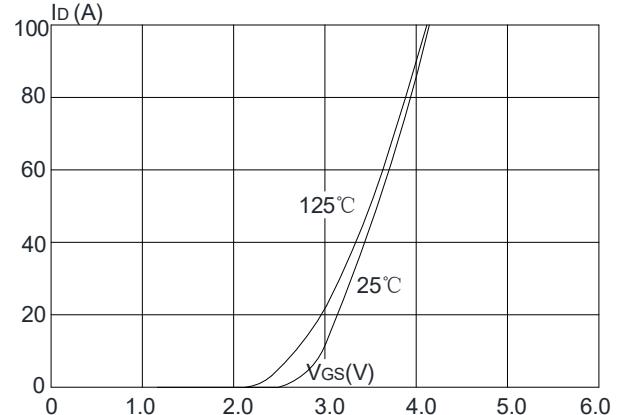
D. Guaranteed by design, not subject to production testing.

## Typical Characteristics

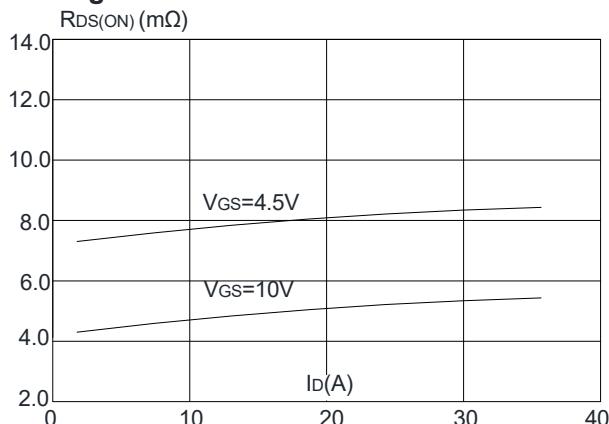
**Figure 1:** Output Characteristics



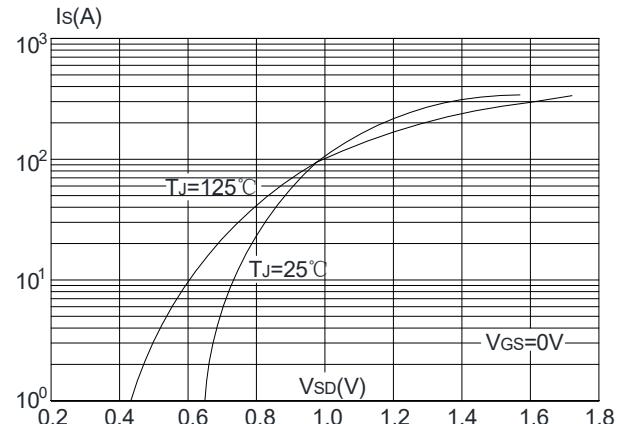
**Figure 2:** Typical Transfer Characteristics



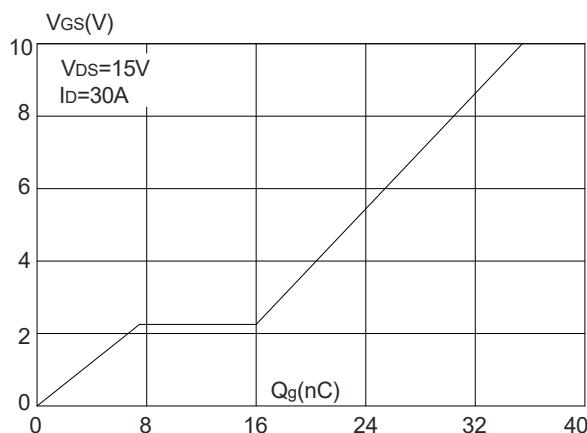
**Figure 3:** On-resistance vs. Drain Current



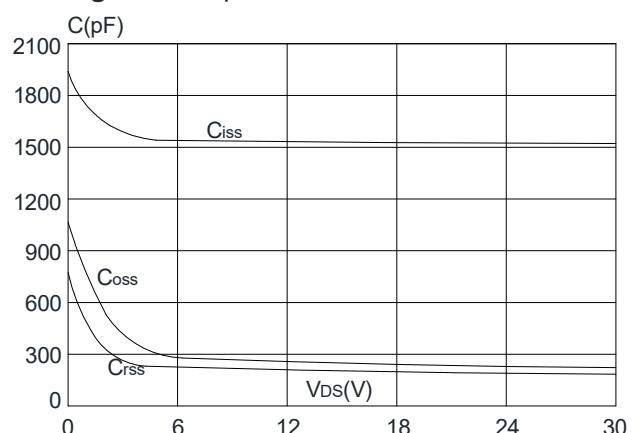
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

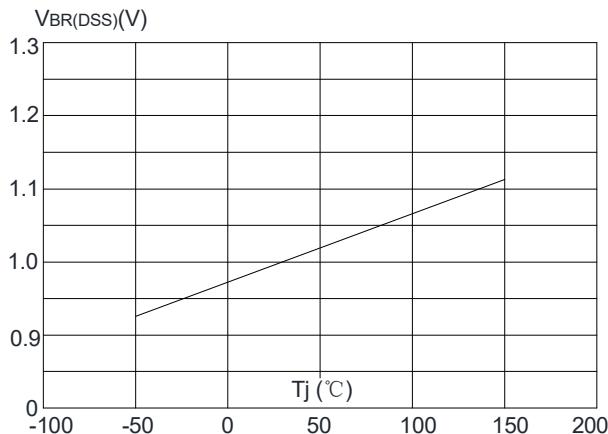


**Figure 6:** Capacitance Characteristics

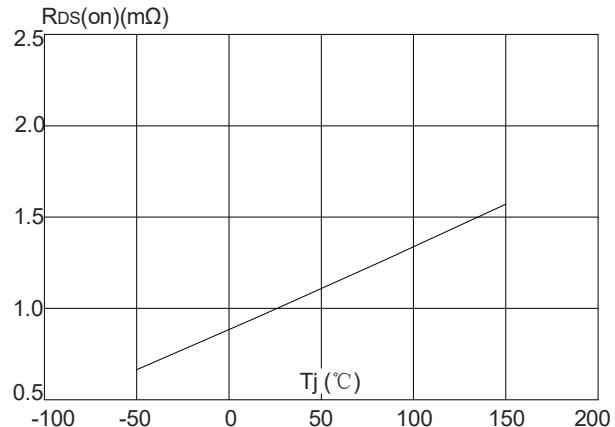


## Typical Characteristics

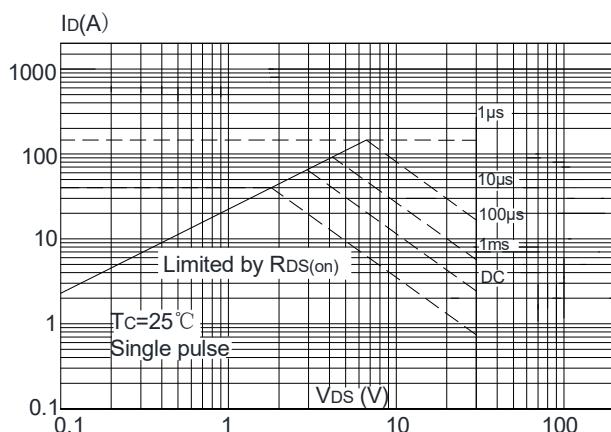
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



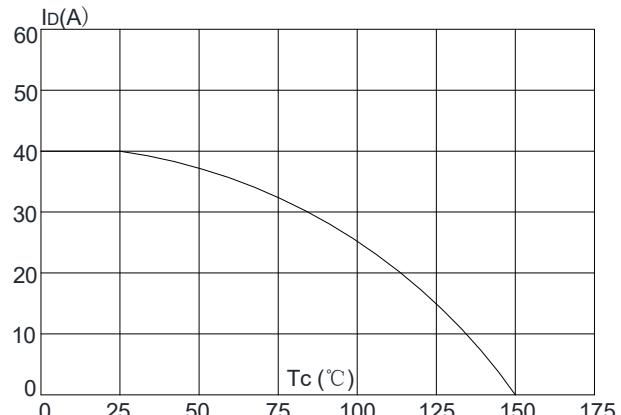
**Figure 8:** Normalized on Resistance vs. Junction Temperature



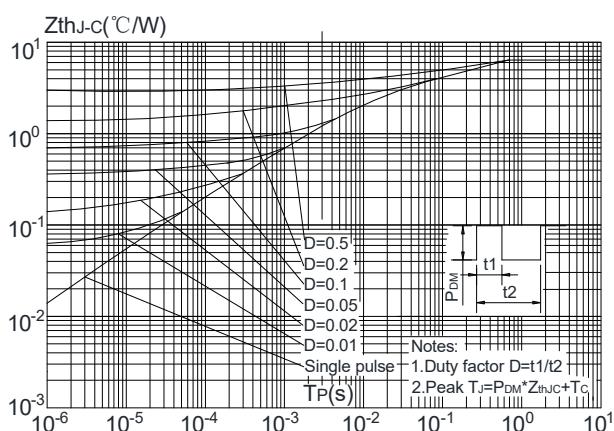
**Figure 9:** Maximum Safe Operating Area

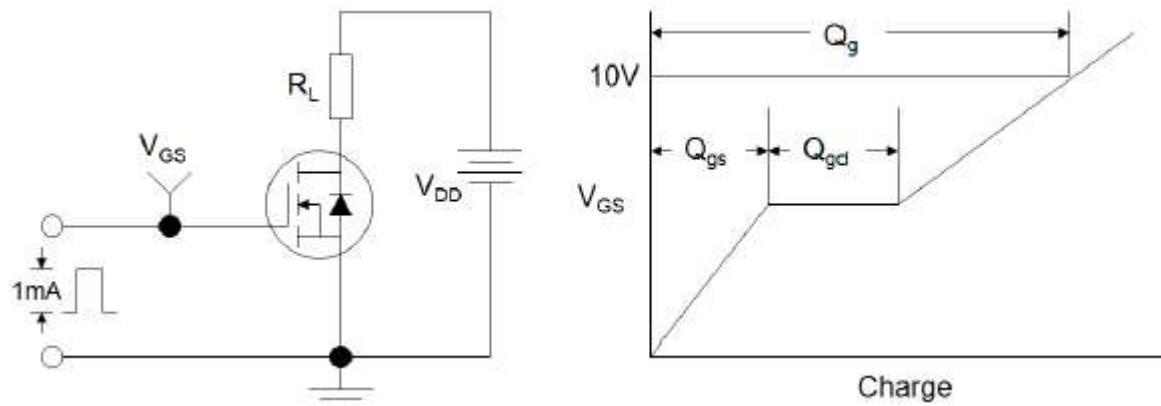
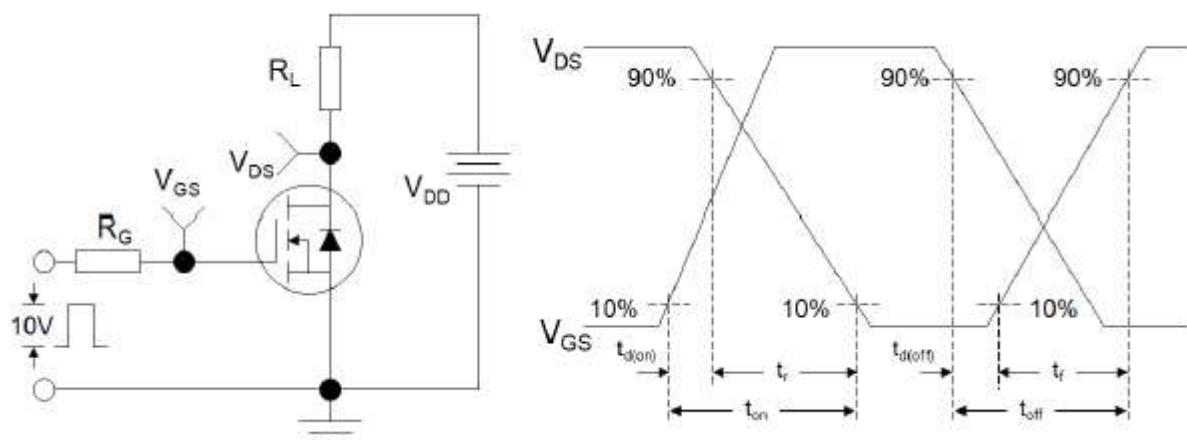
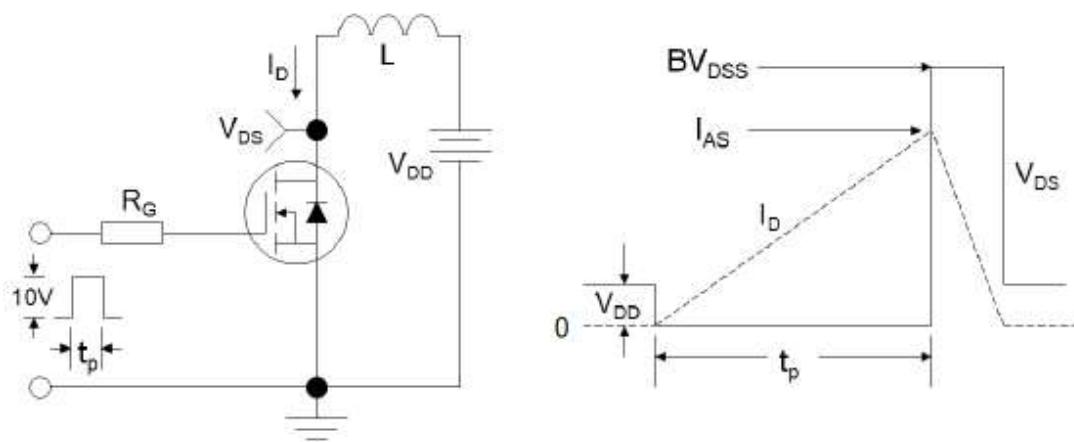


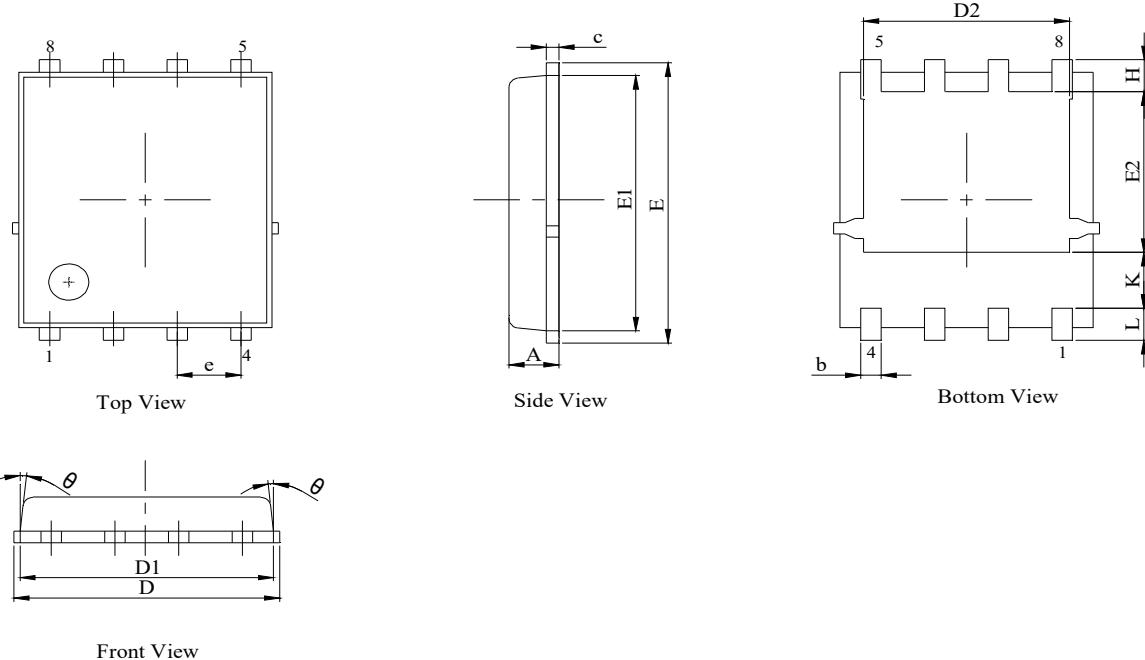
**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Test Circuit**

**Figure1:Gate Charge Test Circuit & Waveform**

**Figure 2: Resistive Switching Test Circuit & Waveforms**

**Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms**

**PDFN5X6-8L Package Information (unit:mm)**


DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
b	0.31	0.41	0.51
c	0.20	0.25	0.30
D	5.00	5.20	5.40
D1	4.95	5.05	5.15
D2	4.00	4.10	4.20
E	6.05	6.15	6.25
E1	5.50	5.60	5.70
E2	3.42	3.53	3.63
e	1.27BSC		
H	0.60	0.70	0.80
L	0.50	0.70	0.80
$\theta$	-	-	10°